Ref	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"ROM" and (semiconductor or wafer or substrate) near4 photoresist and pattern\$4 and (ion near4 implant\$4) and "LDD" and (organic near4 (spacer or sidewall)) and photoresist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 10:31
<b>L2</b>	8	(semiconductor or wafer or substrate) near4 photoresist and pattern\$4 and (ion near4 implant\$4) and "LDD" and (organic near4 (spacer or sidewall)) and photoresist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 11:46
L3	9	(semiconductor or wafer or substrate) near4 photoresist and pattern\$4 and (ion near4 implant\$4) and "LDD" and ((organic or "ARC" or "BARC") near4 (spacer or sidewall)) and photoresist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 12:01
L4	470	(("ARC" or "BARC" or organic) near4 spacer or sidewall) near8 "photoresist pattern"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 12:03
L5	1	(("ARC" or "BARC" or organic) near4 spacer or sidewall) near8 "photoresist pattern" and (semicondcutor or wafer or subsrate) and "LDD" and "HDD" and (ion near4 implant\$8) and strip\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON .	2006/04/07 12:06
L6 .		(("ARC" or "BARC" or organic) near4 spacer or sidewall) near8 "photoresist pattern" and (semicondcutor or wafer or subsrate) and "LDD" and "HDD" and (ion near4 implant\$8)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 12:06
L7	6	(("ARC" or "BARC" or organic) near4 spacer or sidewall) near8 "photoresist pattern" and (semicondcutor or wafer or subsrate) and "LDD" and (ion near4 implant\$8) and strip\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 12:34

L8	137	(("ARC" or "BARC" or organic) near4 spacer or sidewall) near8 "photoresist pattern" and (semicondcutor or wafer or subsrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 13:21
L9	16	(("ARC" or "BARC" or organic) near4 spacer or sidewall) near8 "photoresist pattern" and (semicondcutor or wafer or subsrate) and "LDD"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 12:46
L10	2	(organic near4 (spacer or sidewall)) near8 "photoresist pattern" and (semicondcutor or wafer or subsrate) and "LDD"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 12:54
L11	1	(organic near4 (spacer or sidewall)) near8 "photoresist pattern" and "ROM"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 13:07
L12	. 2	(mask near4 "ROM") and "LDD" and organic near4 (sidewall or spacer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 13:08
L13		(mask near4 "ROM") and "LDD" and (organic near4 (sidewall or spacer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 13:08
L14	3	(mask near4 "ROM") and "LDD" and ((organic or "BARC" or "ARC")near4 (sidewall or spacer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 13:12
L15	2	(("ARC" or "BARC" or organic) near4 spacer or sidewall) near8 "photoresist pattern" and (semicondcutor or wafer or subsrate) and (438/257.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/07 13:21

- 1		*	I	<del></del>	<del></del>	
S1	0	(wafer or semiconductor or substrate) and photoresist and pattern and (ion near implant\$4) and dop\$4 and organic and spacer and sidewall and (strip or remov\$4) and (pair or two or plurality or multipl\$4 or next) same ("ion implant\$4")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/05 08:39
S2	55	(wafer or semiconductor or substrate) and photoresist and pattern and (ion near implant\$4) and dop\$4 and organic and spacer and sidewall and (strip or remov\$4) and (pair or two or plurality or multipl\$4 or next) same implant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/05 10:04
<b>S</b> 3		(wafer or semiconductor or substrate) and photoresist and pattern and (ion near implant\$4) and dop\$4 and organic and spacer and sidewall and (strip or remov\$4) and (pair or two or plurality or multipl\$4 or next) same implant and (anneal or heat or thermal or cur\$4) and (UV or ultra-violet or "ultra violet") and (LDD or "lightly doped drain") and N+ and BARC and "dry etch\$4"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/05 08:42
S4	15	(wafer or semiconductor or substrate) and photoresist and pattern and (ion near implant\$4) and dop\$4 and organic and spacer and sidewall and (strip or remov\$4) and (pair or two or plurality or multipl\$4 or next) same implant and (anneal or heat or thermal or cur\$4) and (UV or ultra-violet or "ultra violet")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/05 09:46
S5	3	(wafer or semiconductor or substrate) and photoresist and pattern and (ion near implant\$4) and dop\$4 and organic and spacer and sidewall and (strip or remov\$4) and (pair or two or plurality or multipl\$4 or next) same implant and (anneal or heat or thermal or cur\$4) and (UV or ultra-violet or "ultra violet") and LDD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/08/05 09:42

S6	0	(wafer or semiconductor or substrate) and photoresist and pattern and (ion near implant\$4) and dop\$4 and organic and spacer and sidewall and (strip or remov\$4) and (pair or two or plurality or multipl\$4 or next) same implant and (anneal or heat or thermal or cur\$4) and (UV or ultra-violet or "ultra violet") and LDD and BARC	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/05 08:43
S7	1	(wafer or semiconductor or substrate) and photoresist and pattern and (ion near implant\$4) and dop\$4 and organic and spacer and sidewall and (strip or remov\$4) and (pair or two or plurality or multipl\$4 or next) same implant and (anneal or heat or thermal or cur\$4) and (UV or ultra-violet or "ultra violet") and LDD and N+	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/05 08:44